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# TriQuint Technology Shrinks Quad-band EDGE PA Modules By 50% For 3G WEDGE Phones

## CuFlip Technology Enables Improved Battery Life, Uses Less Board Space in 3G Wireless Handsets, PDAs and Data Cards

**HILLSBORO, OR (USA) – February 6, 2008** – TriQuint Semiconductor, Inc. (Nasdaq: TQNT), a leading RF front-end product manufacturer and foundry services provider, today announced the first two members of its HADRON II PA Module™ family; the TQM7M5012 and TQM7M5005. These second-generation EDGE PAs were designed using TriQuint's CuFlip™ copper bump technology, improving RF performance while reducing current consumption to provide longer device battery life. Debuting with a 5x5mm footprint, these solutions are 50 percent smaller than the previous generation, providing handset manufacturers additional board space to add other rich features. The HADRON II PA Module™ family will be displayed at the GSMA Mobile World Congress in Barcelona, Spain (11th – 14th Feb. 2008).

The new products build on the success of TriQuint's first-generation HADRON PA Module™ family, found in some of the industry's most popular mobile devices, including Samsung's BlackJack*, LG's Shine* and Chocolate 3G*, Palm's Treo* and HTC's Advantage*. TriQuint's EDGE PA module shipments to 3G phones experienced 178 percent growth in 2007 as TriQuint gained market share, and as WCDMA networks grew to provide 70 percent of the world's commercially launched 3G services[1]. The growth in WEDGE (WCDMA + EDGE) devices was noted by the Global mobile Suppliers Association (GSA) in its January 15, 2008 update[1], which stated "Most WCDMA-HSPA networks combine with EDGE for service continuity and the best user experience."

Tim Dunn, Vice President for Handsets at TriQuint, said "With WiFi and Bluetooth connectivity, FM radios, MP3 players, cameras, and other rich features appearing in more and more 3G phones, design time increases and board space is at a premium. Our CuFlip™ copper bump technology enables us to shrink the module footprint to 5x5mm while extracting heat fror the PA more efficiently and reducing current. The result is improvement in size, performance, cost, and reliability."

Available in EDGE-Polar and EDGE-Linear versions, both products have been optimized to deliver best-in-class current consumption in the critical GMSK mode, which significantly improves handset battery life. The TQM7M5012 for EDGE-Polar applications is aligned with Qualcomm's newest 3G multimode transceivers. Compared to the previous generation, TQM7M5012 offers even lower Rx band noise power level to help eliminate external components in the radio. The TQM7M5005 is designed to work with some of the worlds leading 2.5G and 3G transceivers that require a linear power amplifier. TriQuint has developed RF radio application and evaluation boards for both the TQM7M5012 and the TQM7M5005 to demonstrate the features and compatibility of the devices, thus enabling phone manufacturers to shorten handset development time.

Paul Cooper, Strategic Marketing Manager for Handsets at TriQuint, said "TriQuint's customers can be confident that our silicon partner cooperation enables seamless alignment of the HADRON II PA Module™ family with the transceiver chips, offering a streamlined process for radio design and assembly. We are pleased to provide these benefits in both Polar and Linear versions, servicing the needs of our wide customer base."

**Availability**
TriQuint is currently sampling the TQM7M5005 and the TQM7M5012 to lead customers and production is planned for 1H 2008. Customers interested in obtaining samples and evaluation boards should contact info-handsets@triquint.com

**FORWARD-LOOKING STATEMENTS**
This TriQuint Semiconductor, Inc. (Nasdaq: TQNT) press release contains forward-looking statements made pursuant to the Safe Harbor provisions of the Private Securities Litigation Reform Act of 1995. Readers are cautioned that forward-looking statements involve risks and uncertainties. The cautionary statements made in this press release should be read as being applicable to all related statements wherever they appear. Statements containing such words as 'most popular', 'world-class', 'proven', 'seamless', 'streamlined', or similar terms are considered to contain uncertainty and are forward-looking statements. A number of factors affect TriQuint's operating results and could cause its actual future results to differ materially from any results indicated in this press release or in any other forward-looking statements made by, or on behalf of, TriQuint including, but not limited to: those associated with the unpredictability and volatility of customer acceptance of and demand for our products and technologies, the ability of our production facilities and those of our vendors to meet demand, the ability of our production facilities and those of our vendors to produce products with yields sufficient to maintain profitability, as well as the other "Risk Factors" set forth in TriQuint's most recent 10-Q report filed with the Securities and Exchange Commission. This and other reports can be found on the SEC web site, www.sec.gov. A reader of this release should understand that these and

other risks could cause actual results to differ materially from expectations expressed / implied in forward-looking statements.

**FACTS ABOUT TRIQUINT**

Founded in 1985, we "Connect the Digital World to the Global Network"™ by supplying high-performance RF modules, components and foundry services to the world's leading communications companies. Specifically, TriQuint supplies products to four out of the top five cellular handset manufacturers, and is a leading gallium arsenide (GaAs) supplier to major defense and space contractors. TriQuint creates standard and custom products using advanced processes that include gallium arsenide, surface acoustic wave (SAW) and bulk acoustic wave (BAW) technologies to serve diverse markets including wireless handsets, base stations, broadband communications and military. TriQuint is also lead researcher in a 3-year DARPA program to develop advanced gallium nitride (GaN) amplifiers. TriQuint, as named by Strategy Analytics in August 2007, is the number-three worldwide leader in GaAs devices and the world's largest commercial GaAs foundry. TriQuint has ISO9001 certified manufacturing facilities in Oregon, Texas, and Florida and a production plant in Costa Rica; design centers are located in North America and Germany. Visit TriQuint at www.triquint.com/rf to register for our newsletters.

*Other names property of respective companies.

[1]Global mobile Suppliers Association (GSA) GSM/3G MARKET UPDATE, January 15, 2008

Shane Smith
Director of Marketing
TriQuint Semiconductor, Inc
Tel: +1.503.615.9473
Mobile: +1.407.489.5291
E-mail: ssmith@tqs.com

Paul Cooper
Strategic Marketing Manager
TriQuint Semiconductor, Inc.
Mobile: +1.603.490.7195
E-mail: pcooper@tqs.com

Shannon Rudd
Marketing Communications Mgr
TriQuint Semiconductor, Inc
Tel: +1 503.615.9407
Mobile : +1.503.750.3290
E-mail: srudd@tqs.com